Workshop on Innovative Devices and Systems

Low-dimensional semiconductors for sensors, electronics, energy

Albert Davydov, Materials Science & Engineering Division, NIST

- About NIST : National Measurement Laboratory
- What we do: nanowires and 2D-layers from fabrication to measurements



Customers & Sponsors: SEMATECH

Acknowledgements

- Abhishek Motayed project design S Sensors, Inc.
- Matt King MOCVD growth of GaN films on 4" Si
- Sergiy Krylyuk HVPE growth of GaN and Si NWs
- Kris Bertnes, Norm Sanford MBE growth and spectroscopy of GaN NWs NST
- John Bonevich, Vladimir Oleshko in-situ TEM NST
- Jong-Yoon Ha, Deepak Sharma, Baomei Wen, Ratan Debnath device fabrication/electrical & optical measurements
- Geetha Aluri, Ritu Bajpai, Elissa Williams sensing measurements
- Tony Ivanov's group MoS₂ materials and FETs
- Jim Maslar CVD growth of MoS₂
- Sergey Baryshev GaN field emitters Ouclid Argonne Fermilab
- Brian Bryce SiNW integrated devices on a chip NIS
- Sam Berweger, Pavel Kabos Microwave near-field Imaging of WSe₂









LECTRONICS

National Institute of Standards & Technology

 National Measurement Laboratory: oldest physical science lab in US (1901)

Central Mission:

Support industrial innovation with Measurements, Standards, and Data

- World class facilities, national networks, international reach
- 3000 Employees

Measurement Research

2,200 publications/year

- Standard Reference Data
 - 100 types available
 - 130 million datasets downloaded/year
- Standard Reference Materials 1,300 products available
 - 33,000 units sold/year



6 Laboratories and User Facilities at NIST



Nanowire devices: Hype or a New Horizons?





Semiconductor nanowire front-runners:



Sophia University (Japan)



NW gas- and bio- sensors



Harvard, Technion, NIST, etc.

Integrated nanowire devices on a chip





GaN nanowire chip-scale gas sensors





Sensing Using GaN NW-TiO₂ Nanocluster Hybrids

IEEE Sensors Journal (2013) 13, 1883

NIST





Ultra-sensitive ppb/ppt concentration levels Wide Sensing Range (ppb to %) With one single sensor Dynamic range modulation

Highly Selective

Small, Low-power (use UV-light, no heater)

Multianalyte Capability

Long Operational Life, Reliable

Nanowire devices for "NIST-on-a-chip" program





GaN top-down dry-etch: field-emission pillars





Field-Emission from Single GaN Nanocone



Compact, low-temperature field-emitters for electron source in accelerators







Array of Vertical p-i-n GaN Photodetectors



Goal: Realization of light-weight, low noise, high efficiency nanowire based detectors for wavelengths <425nm coupled to scintillators, suitable for replacing PMT



- Efficient photo-generation of carriers due to direct light access and trapping
- □ High active surface area
- Utilization of non- and semi-polar GaN surfaces
- Unique nanoscale characterization capabilities

Fabrication: top-down (etch) + bottom-up (growth)

STEP 0

GaN Thin-Film Epitaxial Growth on 4 inch Si Substrates



STEP 1

Large-area GaN Cores using Lithography and Etching





NIST

STEP 2

Core-Shell p-i-n Structures by Selective Area Epitaxy

Halide Vapor Phase Epitaxy (HVPE)





Step 2: Array of Core/Shell Pillars by HVPE growth



- **5** mm x 5 mm arrays
- $\hfill \hfill \hfill$
- controlled GaN shell shape and doping

Absence of polarization on m-plane => better control of device performance



GaN device on non-polar plane GaN Si Substrate

NIST

PL on n-Core and n- and p- Shells





Lower strain as Raman & PL data suggest





Photodetection Using p-i-n Core/Shell Diodes









SiNW cantilevers for mass sensing (Brian Bryce) NST



-

WD = 5.4 mm Signal B = InLens

Next steps:

- Integrated optical detection with *near-field* diode (local Fabry-Perot cavity)
- Magnetic actuation? (Est. forces ~ 1 fN -> displacement ~ 10*Q*F)
- CCD integration for stroboscopic mass readout
- Light source integration

NW tips for multi-functional scanning probe





NIST-Boulder



Combine near-field scanning microwave microscopy with near-field scanning optical microscopy using GaN nanowire LED as light source

- Stable tip shape = stable probe capacitance and greater sensitivity to device under test
- Robust tips for hundreds of scans
- 2x higher index of refraction for better light confinement

Kris Bertness, Norm Sanford (NIST-Boulder)

All solid state Li-ion nanowire battery





Fabrication of single nanowire Li-ion battery Nanoletters, 12 (2012) 505



NIST & Center for Nanoscale Science & Technology

I= 0

10

Time (hours)

12

14 16

2hrs17min

18

Single Si NW solid-state battery

NIST & Center for Nanoscale Science & Technology

Working single nanowire battery

NIST & Center for Nanoscale Science & Technology

2D layers: correlating materials modeling with expts. **NST**

CHMaD: Center for Hierarchical Materials Design (Mark Hersam, Lincoln Lahoun, Northwestern Univ.)

Characterizing Precursor Chemistry for MoS₂ CVD

Project Team: J.E. Maslar, W.A. Kimes, B.A. Sperling (MML)

Goal: Identify CVD chemistries for large-area TMDC high-volume manufacturing

Schematic of Deposition System

Optical Mass Flow Meter

Transport measurements: low-frequency noise in MoS₂ FETs

Ref: Electrical transport and low-frequency noise in chemical vapor deposited single-layer MoS2 devices, Nanotechnology (2014) 25, 155702

Microwave near-field Imaging: Sam Berweger, Pavel Kabos (NIST-Boulder)

Image and identify defects and electronic inhomogeneities

Summary: Nanowire devices for on-chip integration

GaN NW sensors:

- multiplexed selectivity tuning by nano-catalysts
- ppb/ppt sensitivity and large operational range
- RT operation (UV-triggered); low power; low degradation
- AIN needles and GaN top-down etched pillars for field-emitters
 - Sharp tips (easy escape for electrons)
 - Stable cathode material as compared to CNT and Si
 - AlN to GaN alloy tunability
- GaN p-n and p-i-n core/shell arrays for LED & PD:
 - access to non-polar surfaces
 - scalability (due to top-down patterning)
 - Potential high-efficiency in photo-detectors (direct light access)
 - Li-ion all-solid-state SiNW batteries:
 - miniaturization
 - high surface area, cathode thinning=>power density increase
- 2D materials and devices:
 - Computational materials design (collaboration with CHiMaD)
 - Correlating electronic structure to transport properties

